

2825/IFW



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Electronic Patent Application Submission

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EFS ID: 67159
Application ID: 10046858 
Title of Invention: Method and apparatus for placing circuit modules
First Named Inventor: Steven Teig
Domestic/Foreign Application: Domestic Application
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Confirmation number: 6767
Attorney Docket Number: SPLX.P0124

Total Fees Authorized:

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TRANSMITTAL

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	Method and apparatus for placing circuit modules	
Application Number:	10/046858	
Date:	2002-01-13	
First Named Applicant:	Steven Teig	
Confirmation Number:	6767	
Attorney Docket Number:	SPLX.P0124	
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Submitted by:	Elec. Sign.	Sign. Capacity
Mani Adeli Registered Number: 39,585	/Mani Adeli/	Attorney

Documents being submitted

us-ids

Files

SPLX.P0124-usidst.xml

us-ids.dtd

us-ids.xsl

Comments



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	Method and apparatus for placing circuit modules											
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Attorney Docket Number:	SPLX.P0124											
Art Unit:	2825											
Examiner:	LEIGH M. GARBOWSKI											
Search string:	(4777606 or 5224057 or 5519836 or 5699265 or 6018623 or 6038385 or 6085032 or 6088519 or 6154874 or 6240541 or 6349403 or 6366279 or 6442745 or 6505331 or 6601227 or 20030014725 or 20040044979).pn.											
US Patent Documents												
Note: Applicant is not required to submit a paper copy of cited US Patent Documents												
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass					
	1	4777606	1988-10-11	Fournier								
	2	5224057	1993-06-29	Igarashi et al.								
	3	5519836	1996-05-21	Gawlick et al.								
	4	5699265	1997-12-16	Scepanovic et al.								
	5	6018623	2000-01-25	Chang et al.								
	6	6038385	2000-03-14	Scepanovic et al.								
	7	6085032	2000-07-04	Scepanovic et al.								
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	9	6154874	2000-11-28	Takahashi								
	10	6240541	2001-05-29	Yasuda et al.								
	11	6349403	2002-02-19	Dutta et al.								
	12	6366279	2002-04-02	Gorman et al.	B1							
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	14	6505331	2003-01-07	Bracha et al.	B1							
	15	6601227	2003-07-21	Trimberger	B1							

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20030014725	2003-01-16	Sato et al.	A1		
	2	20040044979	2004-03-04	Aji et al.	A1		

Signature

Examiner Name	Date